Ordering number : ENN*7056

CMOS IC

LC35V1000BM, BTS-70U

Asynchronous Silicon Gate 1M (131,072 words ×8 bits) SRAM

Preliminary

Overview

The LC35V1000BM and LC35V1000BTS-70U are asynchronous silicon gate CMOS static RAM devices with a 131,072-word by 8-bit structure. They provide two chip enable pins ($\overline{CE1}$ and CE2) for device select/deselect control and one output enable pin ($\overline{OE}$) for output control. They feature high speed, low power, and a wide operating temperature range.This makes them optimal for use in systems that require high speed, low power, and battery backup. They also support easy memory expansion.

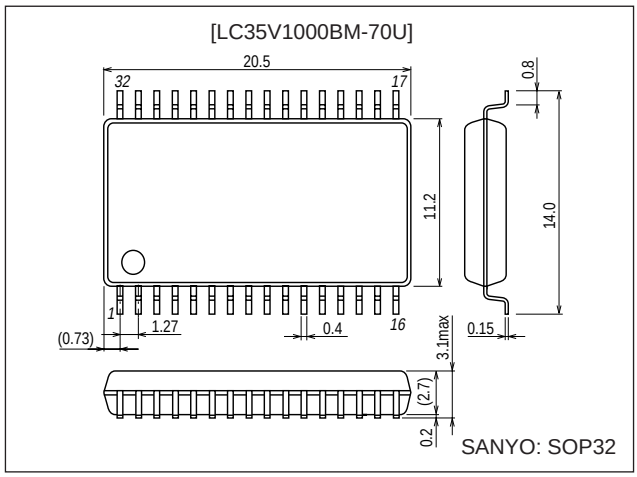
Features

- Low-voltage operation: 3.0 to 3.6 V
- Wide operating temperature range: –40 to +85°C
- Access time: 70 ns (maximum): LC35V1000BM and LC35V1000BTS-70U.
- Low current drain
  Standby mode: 0.05 µA (typical*) at Ta = +25°C *: When V_{CC} = 3.0 V
  10.0 µA (maximum) at Ta = +70°C
  20.0 µA (maximum) at Ta = +85°C
- Data retention voltage: 2.0 to 3.6 V
- No clock required (fully static circuits)
- Input/output shared function pins, 3-state output pins
- Package
  32-pin SOP (525 mil) plastic package: LC35V1000BM
  32-pin TSOP (8 ×14 mm) plastic package: LC35V1000BTS

Package Dimensions

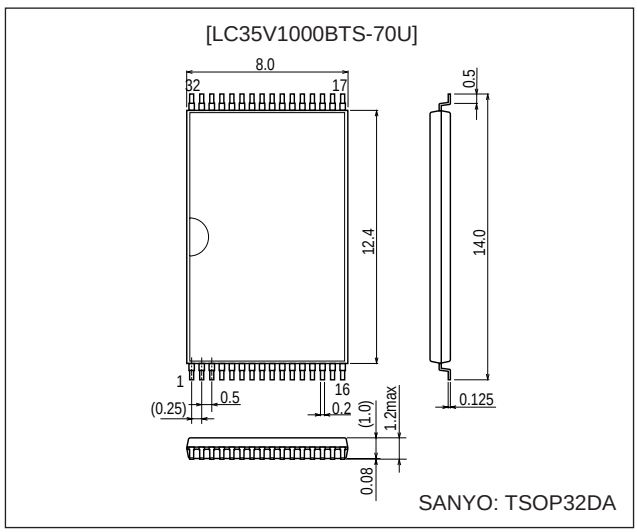
unit: mm

3205A-SOP32



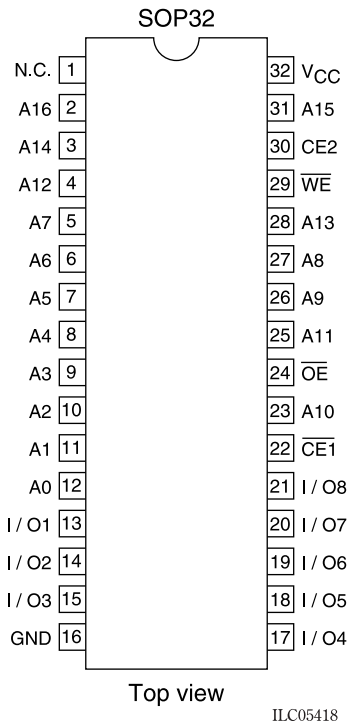
unit: mm

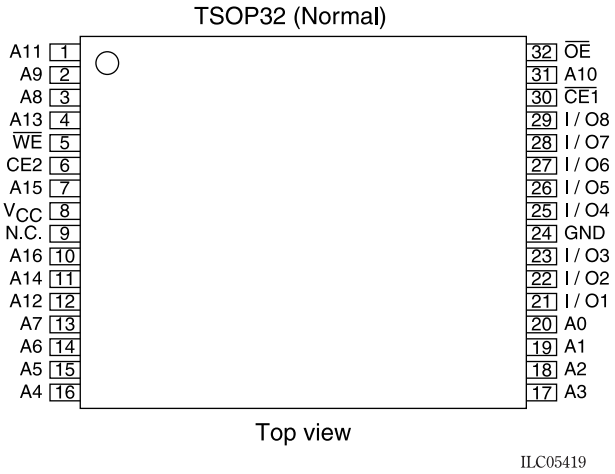
3228A-TSOP32DA



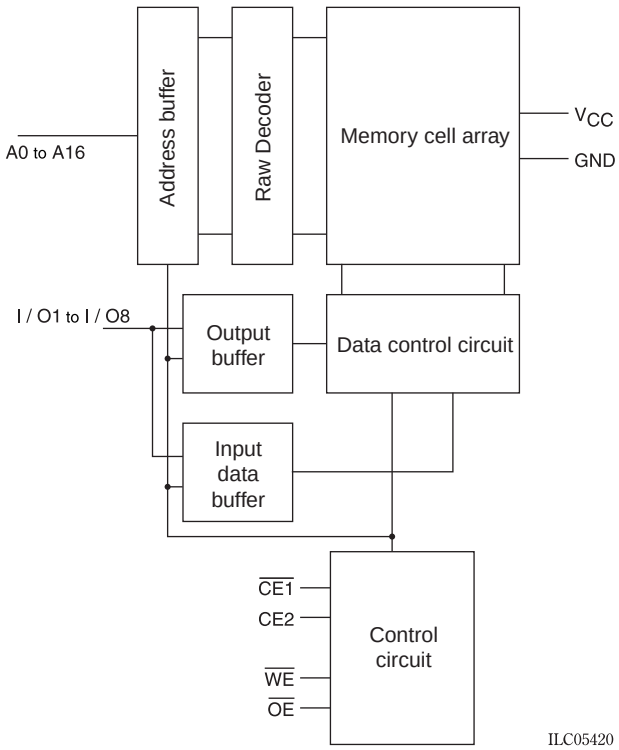
SANYO Electric Co.,Ltd. Semiconductor Company
TOKYO OFFICE Tokyo Bldg., 1-10, 1 Chome, Ueno, Taito-ku, TOKYO, 110-8534 JAPAN

Pin Assignment





Block Diagram



Pin Functions

A0 to A16	Address input
$\overline{WE}$	Ready/write control input
$\overline{OE}$	Output enable input
$\overline{CE}$, CE2	Chip enable input
I/O1 to I/O8	Data I/O
V_{CC}, GND	Power supply, ground

Function Table

Mode	$\overline{CE1}$	CE2	$\overline{OE}$	$\overline{WE}$	I/O	Supply current
Ready cycle	L	H	L	H	Data output	I_{CCA}
Write cycle	L	H	X	L	Data input	I_{CCA}
Output disable	L	H	H	H	High impedance	I_{CCA}
Unselected	H	X	X	X	High impedance	I_{CCS}
	X	L	X	X	High impedance	I_{CCS}

Note: X indicates H or L.

Specifications

Maximum Ratings at Ta = 25°C

Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage	V_{CC} max		4.6	V
Input pin voltage	V_{IN}		–0.3* to V_{CC} + 0.3	V
I/O pin voltage	$V_{I/O}$		–0.3 to V_{CC} + 0.3	V
Operating temperature	Topr		–40 to +85	°C
Storage temperature	Tstg		–55 to +125	°C

*: For pulse widths under 30 ns: –2.0 V

Note: This chip may be destroyed if any stress in excess of the absolute maximum ratings is applied.

I/O Capacitances at Ta = 25°C, f = 1 MHz

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Input capacitance	C_{IN}	V_{IN} = 0 V		6	10	pF
I/O capacitance	$C_{I/O}$	$V_{I/O}$ = 0 V		6	10	pF

Note: These parameters are not measured for all devices, but are sampled values.

DC Allowable Operating Range at Ta = –40 to +85°C

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Supply volgate	V_{CC}		3.0	3.3	3.6	V
High-level input voltage	V_{IH}		$0.8V_{CC}$		V_{CC} + 0.3	V
Low-level input voltage	V_{IL}		–0.3*		$0.2V_{CC}$	V

Note: * The minimum value is –2.0 V for pulse width under 30 ns.

DC Electrical Characteristics at Ta = –40 to +85°C, V_{CC} = 3.0 to 3.6 V

Parameter	Symbol	Conditions		Ratings			Unit
				min	typ	max	
Input leakage current	I_{LI}	V_{IN} = 0 to V_{CC}		–1.0		+1.0	µA
I/O leakage current	I_{LO}	$V_{\overline{CE1}}$ = V_{IH} or V_{CE2} = V_{IL} or $V_{\overline{OE}}$ = V_{IH} or $V_{\overline{WE}}$ = V_{IL}, $V_{I/O}$ = 0 to V_{CC}		–1.0		+1.0	µA
Outpu high-level voltage	V_{OH1}	V_{OH1} = –2.0 mA		V_{CC} – 0.4			V
	V_{OH2}	V_{OH2} = –100 µA		V_{CC} – 0.1			V
Outpu low-level voltage	V_{OL1}	V_{OL1} = 2.0 mA				0.4	V
	V_{OL2}	V_{OL2} = –100 µA				0.1	V
Operating supply current (CMOS inputs)	I_{CCA2}	$V_{\overline{CE1}}$ = V_{IL}, V_{CE2} = V_{IH}, $I_{I/O}$ = 0 mA, V_{IN} = V_{IH} or V_{IL}				1.2	mA
	I_{CCA3}	$V_{\overline{CE1}}$ = V_{IL}, V_{CE2} = V_{IH},	min cycle			25	mA
		$I_{I/O}$ = 0 mA, V_{IN} = V_{IH} or V_{IL}, DUTY100%	1 µs cycle		2		
Standby mode supply current (V_{CC} – 0.2 V/0.2 V inputs) (CMOS inputs)	I_{CCS1}	V_{CE2} ≤ 0.2 V or ($V_{\overline{CE1}}$ ≥ V_{CC} – 0.2 V, V_{CE2} ≥ V_{CC} – 0.2 V)	Ta ≤ 85°C			20	µA
			Ta ≤ 70°C			10	
			Ta ≤ 25°C		0.05		
	I_{CCS2}	$V_{\overline{CE1}}$ = V_{IH} or V_{CE2} = V_{IL}, V_{IN} = 0 to V_{CC}				0.4	mA

Note: * Reference values when V_{CC} = 3.0 V and Ta = 25°C.

AC Electrical Characteristics at Ta = –40 to +85°C, V_{CC} = 3.0 to 3.6 V

AC test conditions

Input pulse voltage levels: V_{IL} = 0.2 V_{CC}, V_{IH} = 0.8 V_{CC}

Input rise and fall times: 5 ns

Input and output timing leves: 0.5 V_{CC}

Output load: 30 pF (including the jig capacitance)

Read cycle

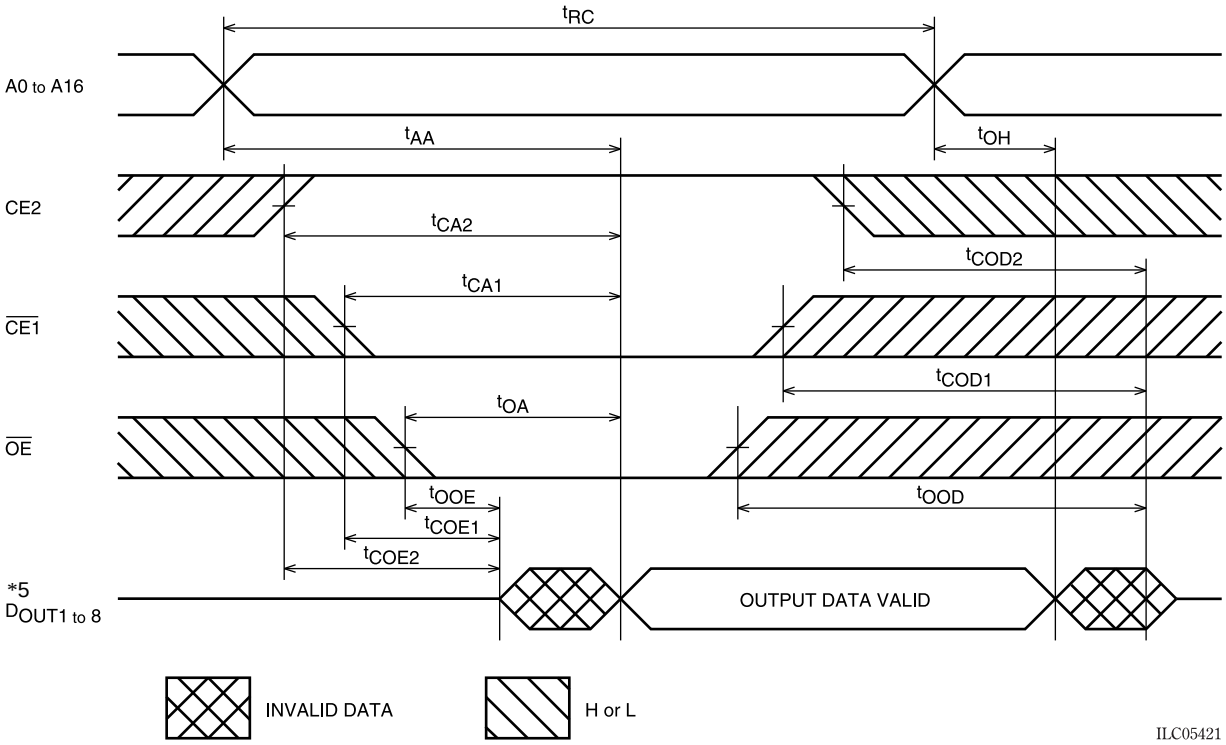
Parameter	Symbol	min	max	Unit
Read cyle time	t_{RC}	70		ns
Address access time	t_{AA}		70	ns
$\overline{CE1}$ access time	t_{CA1}		70	ns
CE2 access time	t_{CA2}		70	ns
$\overline{OE}$ access time	t_{OA}		40	ns
Output hold time	t_{OH}	10		ns
$\overline{CE1}$ output enable time	t_{COE1}	5		ns
CE2 output enable time	t_{COE2}	5		ns
$\overline{OE}$ output enable time	t_{OCE}	0		ns
$\overline{CE1}$ output disable time	t_{COD1}		35	ns
CE2 output disable time	t_{COD2}		35	ns
$\overline{OE}$ output disable time	t_{OOD}		30	ns

Write cycle

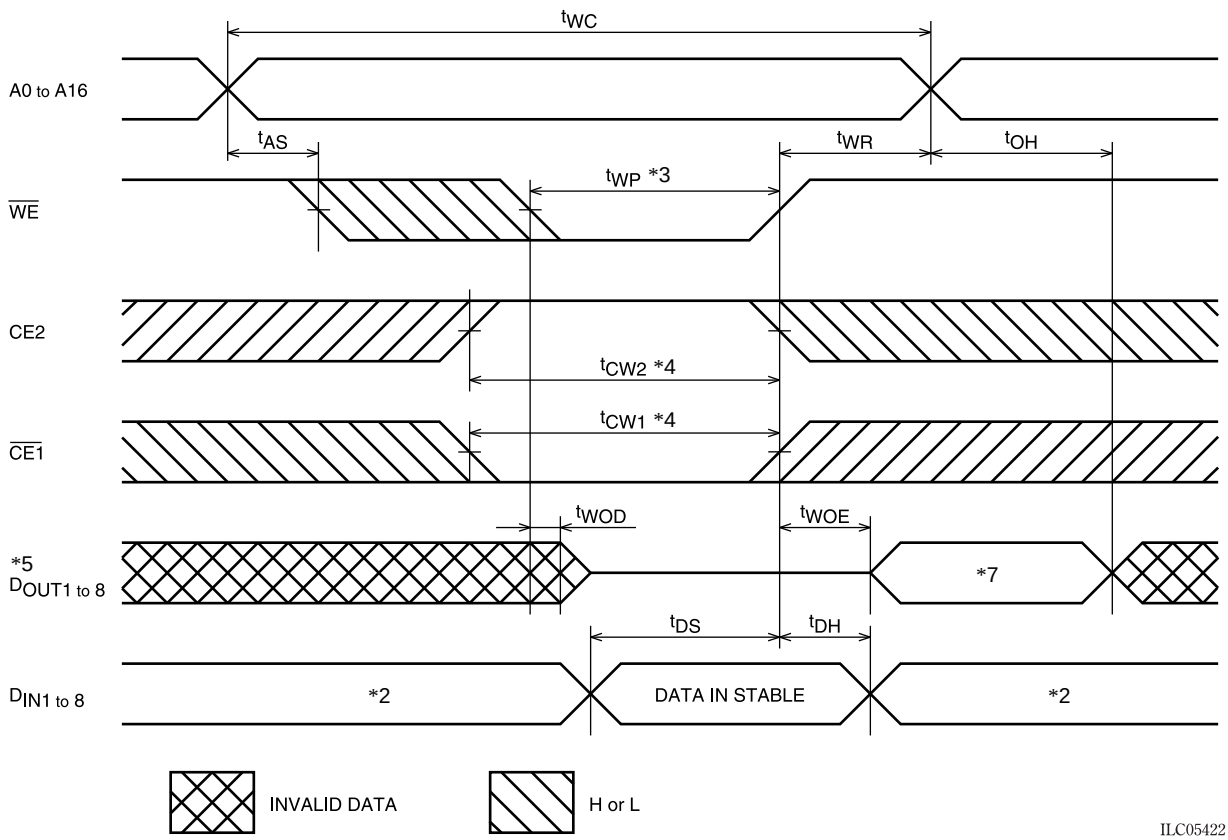
Parameter	Symbol	min	max	Unit
Write cyle time	t_{WC}	70		ns
Address setup time	t_{AS}	0		ns
Write pulse width	tWP	50		ns
$\overline{CE1}$ setup time	t_{CW1}	60		ns
CE2 setup time	t_{CW2}	60		ns
Write recovery time	t_{WR}	0		ns
$\overline{OE1}$ write recovery time	t_{WR1}	0		ns
CE2 write recovery time	t_{WR2}	0		ns
Data setup time	t_{DS}	40		ns
Data hold time	t_{DH}	0		ns
$\overline{OE1}$ data hold time	t_{DH1}	0		ns
CE2 data hold time	t_{DH2}	0		ns
$\overline{WE}$ output enable time	t_{WOE}	5		ns
$\overline{WE}$ output disable time	t_{WOD}		35	ns

Timing Charts

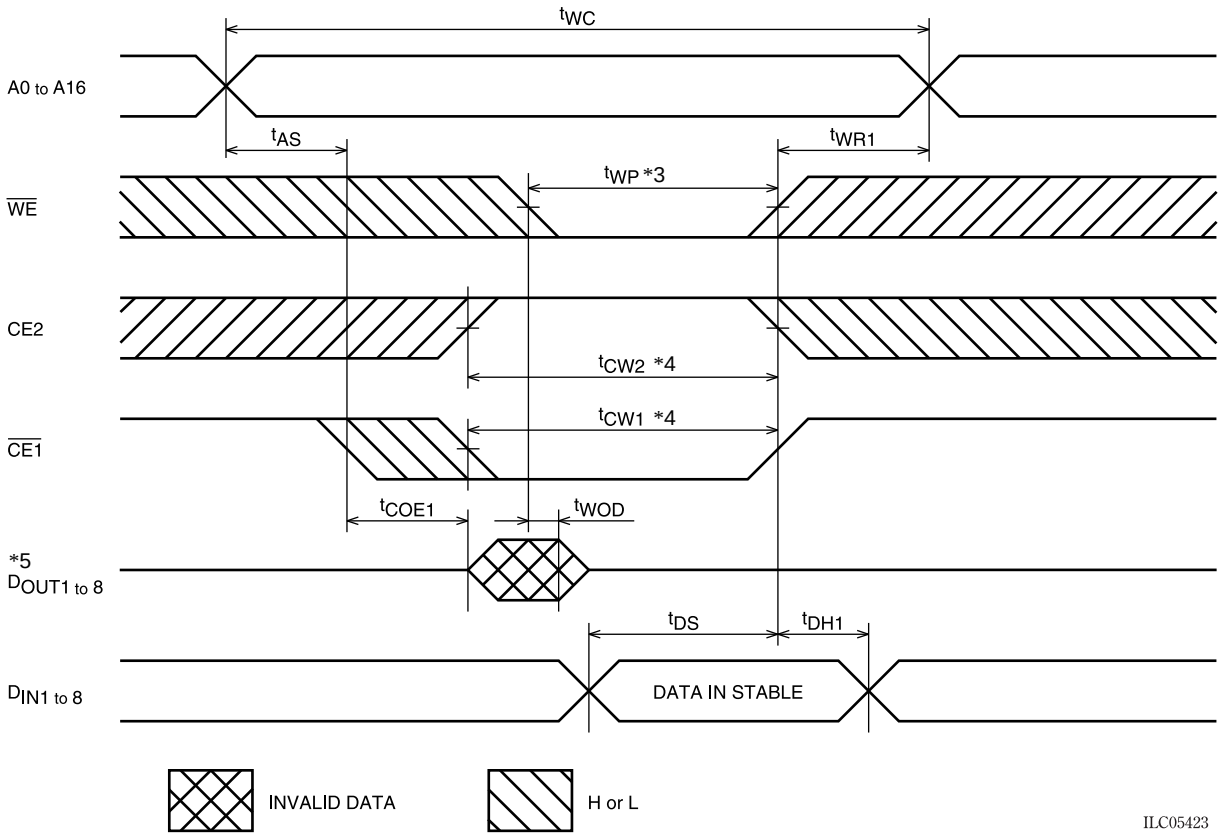
Read cycle (1)



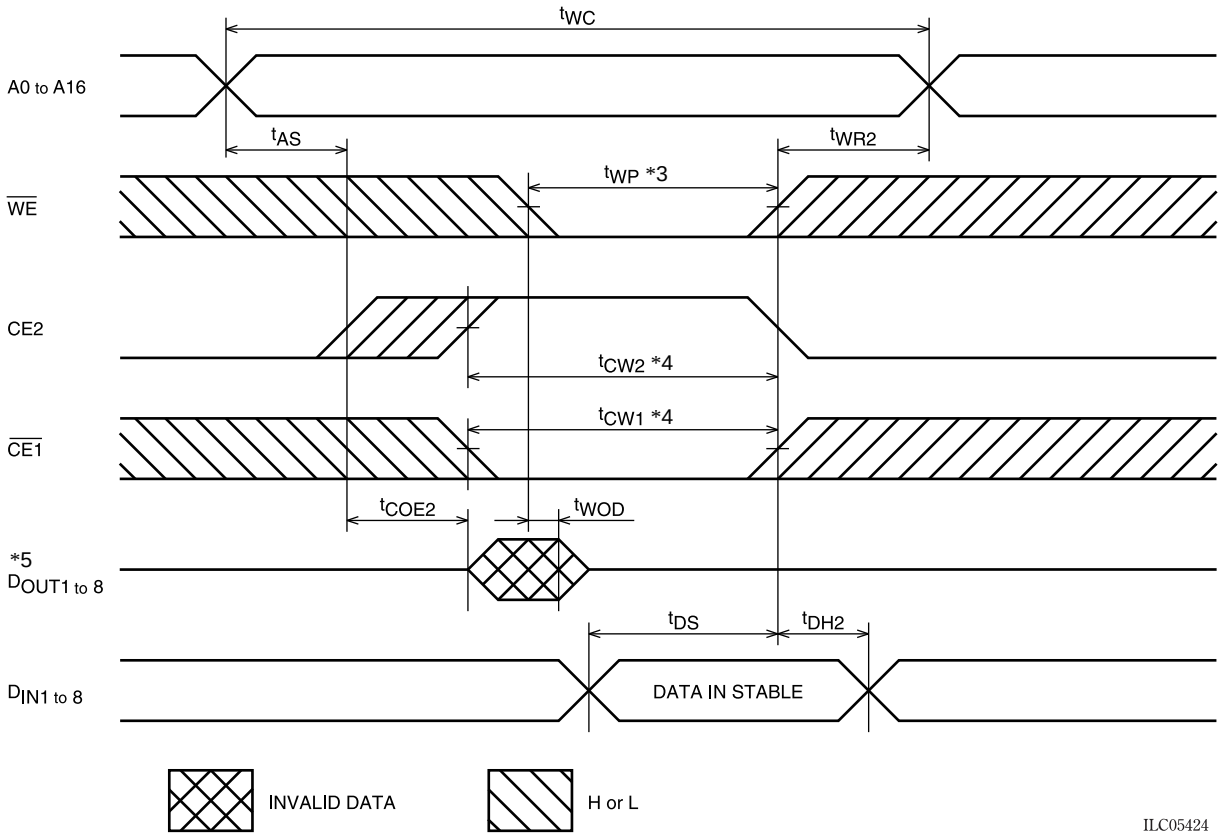
Write cycle (1) ($\overline{WE}$ write)



Write cycle (2) ($\overline{CE1}$ write)



Write cycle (2) (CE2 write)



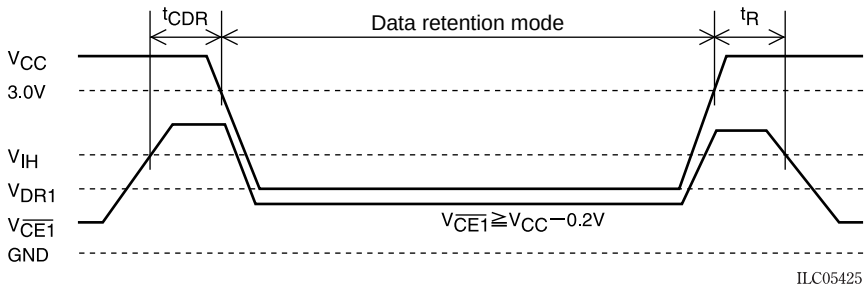
Notes: 1. The times t_{COD1}, t_{COD2}, t_{OOD}, and t_{WOD} are stipulated as the times until the output reaches the high-impedance state. They are not stipulated by output voltage level.
2. Do not apply reverse phase signals to the data outputs when the data outputs are in the output state.
3. t_{WP} is the period that $\overline{CE1}$ and $\overline{WE}$ are at the low level and CE2 is at the high level, and is defined as the time from the fall of $\overline{WE}$ until the rise of $\overline{CE1}$ or $\overline{WE}$ or the fall of CE2, whichever occurs first.
4. t_{CW1} and t_{CW2} are the period that $\overline{CE1}$ and $\overline{WE}$ are at the low level and CE2 is at the high level, and are defined as the time from the fall of $\overline{CE1}$ or the rise of CE2 to the rise of either $\overline{CE1}$ or $\overline{WE}$ or the fall of CE2, whichever occurs first.
5. The data outputs go to the high-impedance state when any one of the following states hold: $\overline{OE}$ is at the high level, $\overline{CE1}$ is at the high level, CE2 is at the low level, or $\overline{WE}$ is at the low level.
6. If $\overline{OE}$ is at the high level during the write cycle, the data outputs will go to the high-impedance state.

Data Retention Characteristics at Ta = –40 to +85°C

Parameter	Symbol	Conditions		Ratings min	Ratings typ	Ratings max	Unit
Data retention supply voltage	V_{DR1}	$V_{\overline{CE1}} \geq V_{CC} - 0.2$ V, $V_{CE2} \geq V_{CC} - 0.2$ V or $V_{CE2} \leq 0.2$ V		2.0		3.6	V
	V_{DR2}	$V_{CE2} \leq 0.2$ V		2.0		3.6	V
Data retention supply current	I_{CCDR1}	V_{CC} = 3.0 V, $V_{\overline{CE1}} \geq V_{CC} - 0.2$ V,	–40°C to +85°C			16	µA
		$V_{CE2} \geq V_{CC} - 0.2$ V,	–40°C to +70°C			8	
		or $V_{CE2} \leq 0.2$ V	+25°C		0.05		
Chip enable setup time	t_{CDR}			0			ns
Chip enable hold time	t_R			5			ms

Note: * Ta = +25°C

Data Retention Waveforms (1) ($\overline{CE1}$ control)



Data Retention Waveforms (2) (CE2 control)